Material Composition Data Sheet

Contact Information
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Manufacturer	Total mass of component specified in (g)	Package	Material name	Substance name	Content(%)	Substance mass (mg)
MCC	0.330	DO-41	Lead Wire	Copper(Cu)	99.98	231.000
				other	0.02	0.050
			Solder Preform	Lead(Pb)	92.50	1.299
				Tin(Sn)	5.00	0.070
				Silver (Ag)	2.50	0.035
			Diode Dice	Silicon (Si)	100.00	0.940
			Molding Compound	SiO_2	69.00	62.100
				Epoxy Resin	20.00	18.000
				Phenol resin	10.00	9.000
				Sb_2O_3	1.00	0.900
			Plating Material	Tin(Sn)	100.00	6.500
					Total mass (mg)	329.894

Lead in internal solder preform, RoHS exemption clause Annex 7a " Lead in high melting temperature type solders " applied.

Materials Disclosure Disclaimer: Even though all possible efforts have been made to provide you with the information, It is for guidance only and we cannot guarantee to its accuracy or completeness.